

In the Specification:

Please replace the paragraph beginning at page 6, line 1, with the following rewritten paragraph:

-- With reference to Figure 1a, there is shown a substrate 1, such as a conventional laminate substrate, as used, for example, in flip chip plastic ball grid array (FC/PBGA) packages. However, it should be understood that substrate 1 may be any of a variety of conventional substrate materials. Solder pads 3 and 5 are presoldered to circuit contacts (not shown) on substrate 1. As shown, the pads may be preformed in generally a mound-like shape. The solder may, for example, be a eutectic composed of 63% Sn/37%Pb. However, other solder compositions may be employed. Capacitor 7 is shown above the substrate ready for positioning thereon. Before positioning capacitor 7 onto substrate 1, a liquid resin noflow underfill material 9 is dispensed onto substrate 1, between and in contact with solder pads 3 and 5. The resin may be a filled or unfilled resin. Typically the noflow material is dispensed as a mound to cover the highest point, or about one half or slightly more than one half, of the solder pads, as shown in Figure 1b. The main consideration is that there is sufficient underfill to cover the peak of the solder pads when capacitor 7 is fully pressed into place, as shown in Figure 1c. However, other forms of noflow underfill application are possible as long as the underfill completely fills the region between ~~pad~~ pads 3 and 5 without voids extending from one pad to the other, and is spread in a sufficiently thick layer so as to extend to cover the peaks or highest points of pads 3 and 5. --

Serial No.:

Please replace the paragraph beginning at page 6, line 21, with the following rewritten paragraph:

-- The dispensing step may be carried out using fluid dispenser, pin transfer, fluid jetting or other application methods. The dispensed noflow material may be, for example, Kester Se-Cure 9101 reflow encapsulant. However, other commercially available reflow materials, such as Dexter Hysol FF 2000 or 2200, Emerson & Cuming Amicon E1350, Alpha Metals Staychip NUF-DP0071 underfill encapsulants, may also be used. Other suppliers, such as Shin Etsu, Namics, Ablestik, and 3M make similar products. These liquid noflow or reflow encapsulants all provide a flux for eutectic solder formation and ~~an~~ a resin so as to form an epoxy-based underfill encapsulant with flux combined into a one part epoxy system. All are particularly developed and designed for flip-chip applications.

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